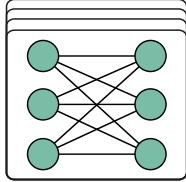




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Deliverable

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1. Publishable summary

This report presents the development of new process modules to integrate shrunk OxRAM bitcells with focus on the main key integration steps and shows the major morphological achievements. More concretely, this report describes the process development to finish the 28nm base wafers with OxRAM memory cells. This is a required step to enable the implementation of some of the neuromorphic circuits designed in WP4.